



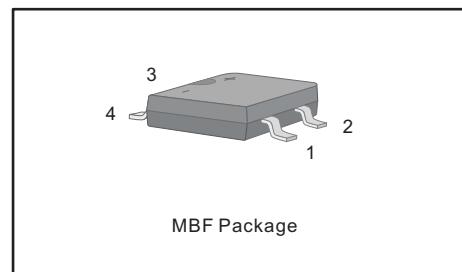
1.2A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

- Glass Passivated Chip Junction
- Reverse Voltage - 1000 V
- Forward Current - 1.2A
- High Surge Current Capability
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



MECHANICAL DATA

- Case: MBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 75mg 0.0026oz

Maximum Ratings and Electrical characteristics

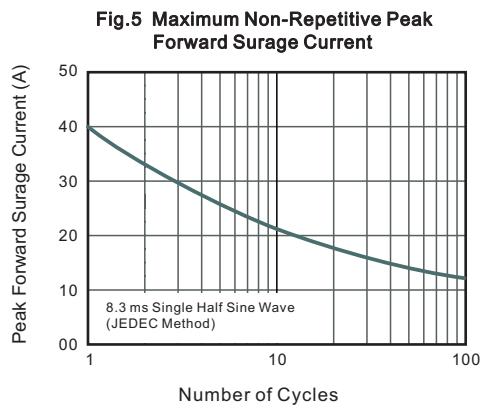
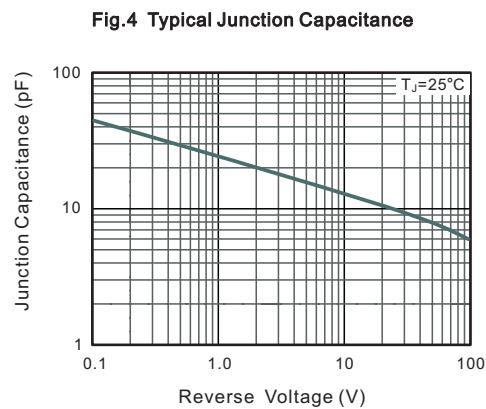
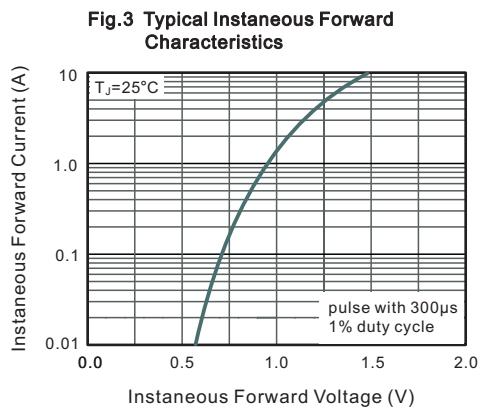
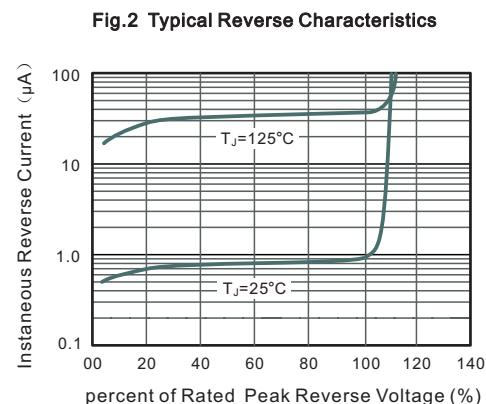
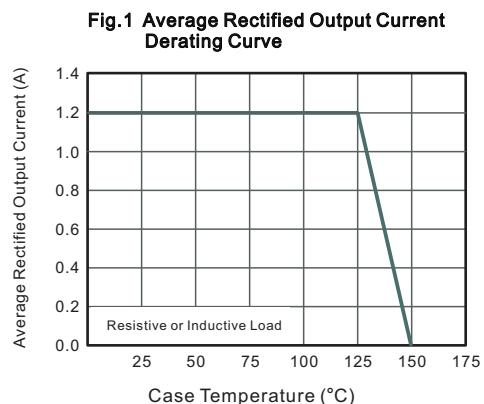
Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	GMB10F-12	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Average Rectified Output Current at $T_c = 125^\circ\text{C}$	I_o	1.2	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	40	A
Maximum Forward Voltage at 1.2 A	V_F	1.1	V
Maximum DC Reverse Current @ $T_A = 25^\circ\text{C}$ @ $T_A = 125^\circ\text{C}$	I_R	5 80	μA
Typical Junction Capacitance (Note1)	C_j	18	pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$ $R_{\theta JC}$	75 22	°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

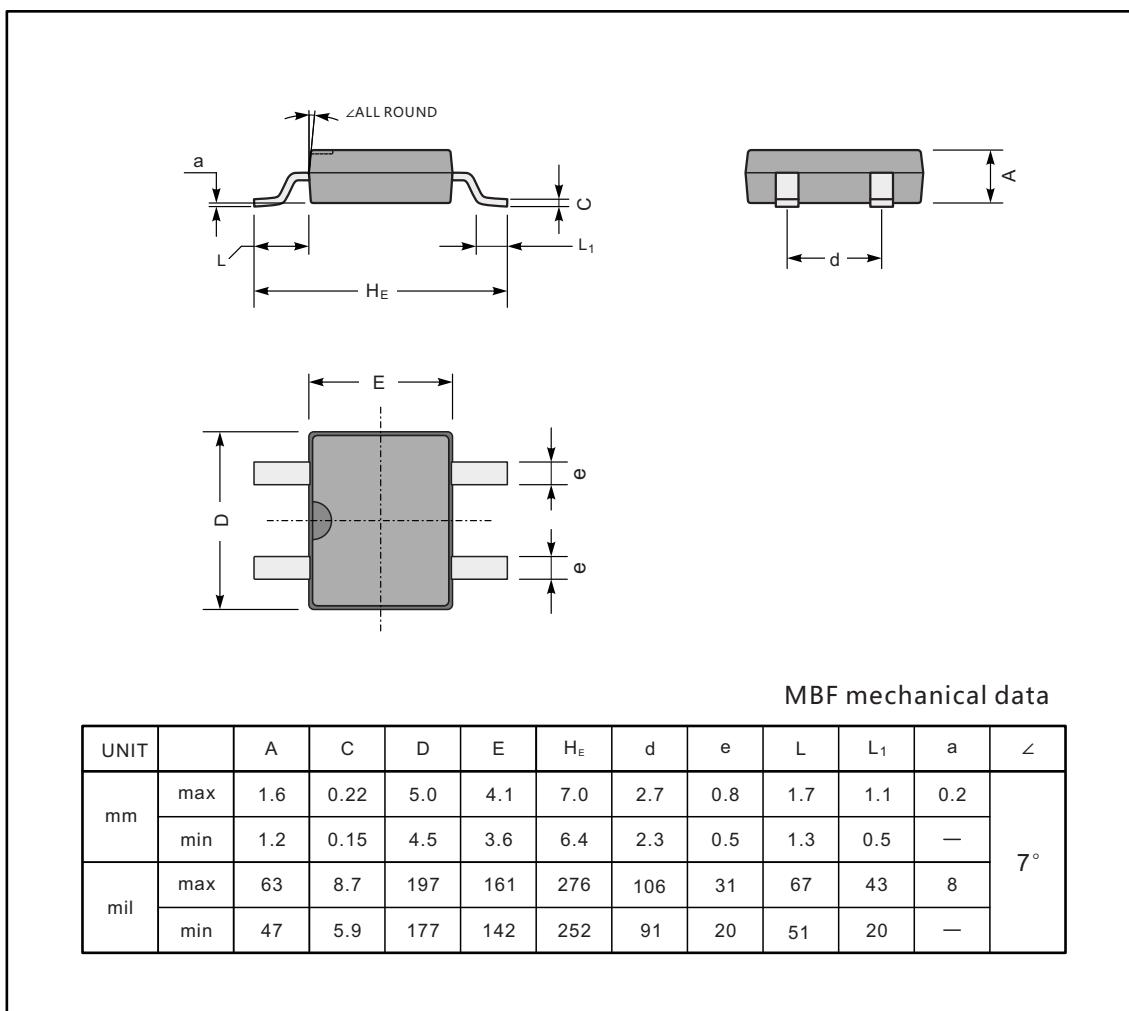




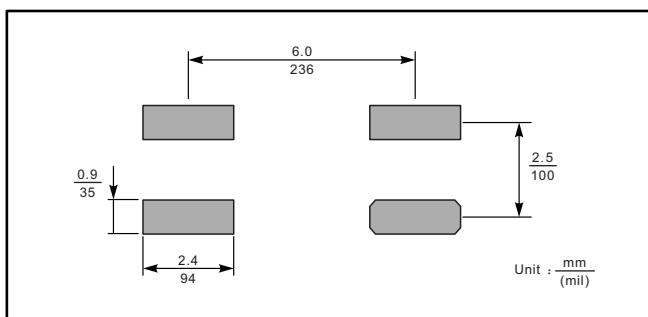
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

MBF



The recommended mounting pad size



Marking

Type number	Marking code
GMB10F-12	G12M10